

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	457	(die or chip or semiconductor) same package same (liquid same cooling)	US-PGPUB ; USPAT ; EPO ; JPO ; DERWE NT ; IBM_T DB	2005/01/04 08:59			
2	BRS	L2	136	1 and cavity	US-PGPUB ; USPAT ; EPO ; JPO ; DERWE NT ; IBM_T DB	2005/01/04 08:22			
3	BRS	L3	0	2 not 1	US-PGPUB ; USPAT ; EPO ; JPO ; DERWE NT ; IBM_T DB	2005/01/04 08:22			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
4	BRS	L4	321	1 not 2	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/04 08:22			
5	BRS	L5	937	(die or chip or semiconductor) same package same (spring\$1 same contact\$1)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/04 08:41			
6	BRS	L6	37	1 and 5	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/04 08:44			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
7	BRS	L7	238	5 and cavity	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/04 08:45			
8	BRS	L8	33	(die or chip or semiconductor) same package same (immersion same cooling)	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/04 09:04			
9	BRS	L9	699	5 not 7	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/04 09:04			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
10	BRS	L10	149	9 and cooling	US- PGPUB ; USPAT ; EPO; JPO; DERWE NT; IBM_T DB	2005/01/04 09:05			